



FINAL PRODUCT/PROCESS CHANGE NOTIFICATION
Generic Copy

12-OCT-2004

SUBJECT: ON Semiconductor Final Product/Process Change Notification #13701

TITLE: Leadform T0220 Assembly Transfer to SBN from Tesla

EFFECTIVE DATE: 12-Dec-2004

AFFECTED CHANGE CATEGORY: ON Semiconductor Assembly/Test Site

AFFECTED PRODUCT DIVISION: Analog Products

ADDITIONAL RELIABILITY DATA: Available

Contact your local ON Semiconductor Sales Representative or Bob Marquis <FC88FC@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Representative or Jaroslav Supina <FFBX3N@onsemi.com>

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact Sales Representative or Alan Garlington <RRP180@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 60 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:

Final Product Change Notice to notify customers of the qualification of the ON Semiconductor Seremban factory for assembly and test of T0220 packages with Leadforming options. Initial Product Change Notice number 13276 was issued on December 19, 2003 which provided advance notice for this change. Related Final Product Change Notice number 13462 was issued on May 6, 2004 which qualified the majority of the T0220 devices. The Seremban factory already produces many other packaged products and is ISO9001:2000 and TS16949 certified.

In addition to the change of location, two other modifications have been made to the T0220 package.

- 1) T0220 Lead finish plating will change from a solder dip process to a Tin Lead or Tin Plated process.
- 2) Lead finish plating will be performed prior to the parts being trimmed from the lead frame. There will be a small area of exposed copper showing at the edge of the heat sink.

Customers may receive product for the D2PAK package styles from either the current Tesla, Czech Republic factory or the new Seremban, Malaysia factory in the future.


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RELIABILITY DATA SUMMARY:

Device Tested: MC33167T

Number of Lots Tested: 3

Test	Conditions	Interval	Rejects	Sample
Autoclave	Ta=121C, P = 15PSIG RH = 100%	96 Hrs	0	231
Temp Cycle	Ta = -65 to 150C	500 Cycle	1*	231
		1000 Cycle	0	230
High Temp Storage	Ta = 150C	504 Hrs	0	231
		1008 Hrs	0	231
High Temp Op Life	Ta = 125C with Bias Vin = 40 v.	504 Hrs	0	231
		1008 Hrs	0	231
HAST	Ta = 130C, RH=85% Vin = 10 v.	96 Hrs	0	231
Solder Heat	Ta = 260C, 10 Sec Dwell	1X	0	135
Solderability	Steam Age = 8Hr, Ta = 245C	1X	0	30

* Failure Analysis indicated failure not related to assembly

ELECTRICAL CHARACTERISTIC SUMMARY:

Electrical data has not changed.

CHANGED PART IDENTIFICATION:

Assembly lot traceability codes can be used to determine the factory used for assembly.

AFFECTED DEVICE LIST (WITHOUT SPECIALS):
PART

LM2575TV-005
 LM2575TV-012
 LM2575TV-015
 LM2575TV-3.3
 LM2575TV-ADJ
 LM2576TV-005
 LM2576TV-012
 LM2576TV-015
 LM2576TV-3.3
 LM2576TV-ADJ
 LM2931ACTV
 MC33166TH
 MC33166TV
 MC33167TH
 MC33167TV
 MC34166TH
 MC34166TV



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MC34167TH
MC34167TV
SC33167TV
SC34166TV
TCM2575-12.0VBV
TCM2575-3.3VBV
TCM2575-5.0VBV
TCM2575VBV
TCM2576-12.0VBV
TCM2576-5.0VBV
TCM2576VBV
TYA7805CTV
TYA7805CTVG
TYA7809CTV
TYA7809CTVG